iC-HG Evaluation Board Selector

Board	Usable Package Types
HG1D	General purpose evaluation board for leaded packages; may not yield iC-HG's maximum switching speed, depending on operating point, actual wiring, and package
HG2M	High-Speed Module for C-mount packages
HG8M	High-Speed Module for TO type or other leaded packages (e.g. butterfly); effective switching speed depends on package inductance
HG20M	High-Speed Module for SMD packages, e.g. for Power-VCSEL arrays
HG21M	High-Speed Module for SMD packages with alternative pad layout
HG2D	Host adapter for easy handling of the above high-speed modules and easy heatsink mounting